

AMENDMENTS TO THE CLAIMS

1. (Original) A circuit assembly, comprising:
 - a circuit substrate with a first set of circuitry;
 - a bonding pad mounted to a surface of the circuit substrate electrically coupled to the first set of circuitry;
 - a flexible circuit substrate with a second set of circuitry;
 - a connecting pad mounted to a surface of the flexible circuit substrate facing the surface of the circuit board and electrically coupled to the second set of circuitry;
 - a ball of conductive material mounted on the bonding pad; and
 - a clamping device to press the connecting pad to the ball of conductive material.
2. (Original) The circuit assembly of claim 1, wherein the ball of conductive material is gold.
3. (Original) The circuit assembly of claim 1, wherein the ball of conductive material is solder.
4. (Original) The circuit assembly of claim 1, wherein the bonding pad is gold coated.
5. (Original) The circuit assembly of claim 1, wherein a solder bump is placed on the bonding pad.

6. (Original) The circuit assembly of claim 1, further comprising:
a plurality of bonding pads coupled to the surface of the circuit substrate;
a plurality of connecting pads coupled to the surface of the flexible circuit substrate
facing the surface of the circuit board; and
a ball of conductive material mounted on each bonding pad.
7. (Original) The circuit assembly of claim 1, wherein the clamping device is one of a
group including a screw and nut, a pin, and a clip.
- 8-14 (Cancelled)
15. (Original) A method, comprising:
mounting a bonding pad to a surface of a circuit substrate;
electrically coupling a first set of circuitry of the circuit substrate;
mounting a connecting pad to a surface of a flexible circuit substrate facing the surface of
the circuit substrate;
electrically coupling a second set of circuitry of the flexible circuit substrate;
mounting a ball of conductive material on the bonding pad; and
clamping the connecting pad to the ball of conductive material.
16. (Original) The method of claim 15, wherein the ball of conductive material is gold.

17. (Original) The method of claim 15, wherein the ball of conductive material is solder.
18. (Original) The method of claim 15, wherein the bonding pad is gold plated.
19. (Original) The method of claim 15, wherein a solder bump is placed on the bonding pad.
20. (Original) The method of claim 15, further comprising:
 - coupling a plurality of bonding pads to the surface of the circuit board;
 - coupling a plurality of connecting pads to the surface of the flexible circuit substrate facing the surface of the circuit substrate; and
 - mounting a ball of conductive material on each bonding pad.